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Abstract Amendments

Please replace the Abstract with the following replacement paragraph as follows:

photolithographic dual damascene trench patterning process is disclosed including providing an inter-metal dielectric (IMD) layer including at least one via opening extending through a thickness thereof; and, conformally forming an antireflectance coating (ARC) layer over said the IMD layer such that the ARC layer is formed over sidewalls of the at least one via opening to reduce light reflectance.